

ABSTRACT OF THE DISCLOSURE

The object of the present invention is to form individual packaged ICs by using a single apparatus to cut wiring boards on which a plurality of IC chips are mounted.

The first cutting device 23 cuts the wiring boards 3 into separate parts along one direction, so that the cut wiring boards 3 constitute strip-form cut wiring boards 3a. The cut wiring boards 3a are conveyed to the second cutting device 33, and are fed [into the second cutting device 33] by the second conveying device 43 along the direction of length. [The cut wiring boards 3a] are then cut by the second cutting device 33 with the orientation altered by 90 degrees relative to the first cutting direction. The wiring boards 3b resulting from the cutting performed by the second cutting device 33 constitute the original forms of the IC packages. The wiring boards 3b that have been cut and conveyed from the second cutting device 33 enter a cleaning step.

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